



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

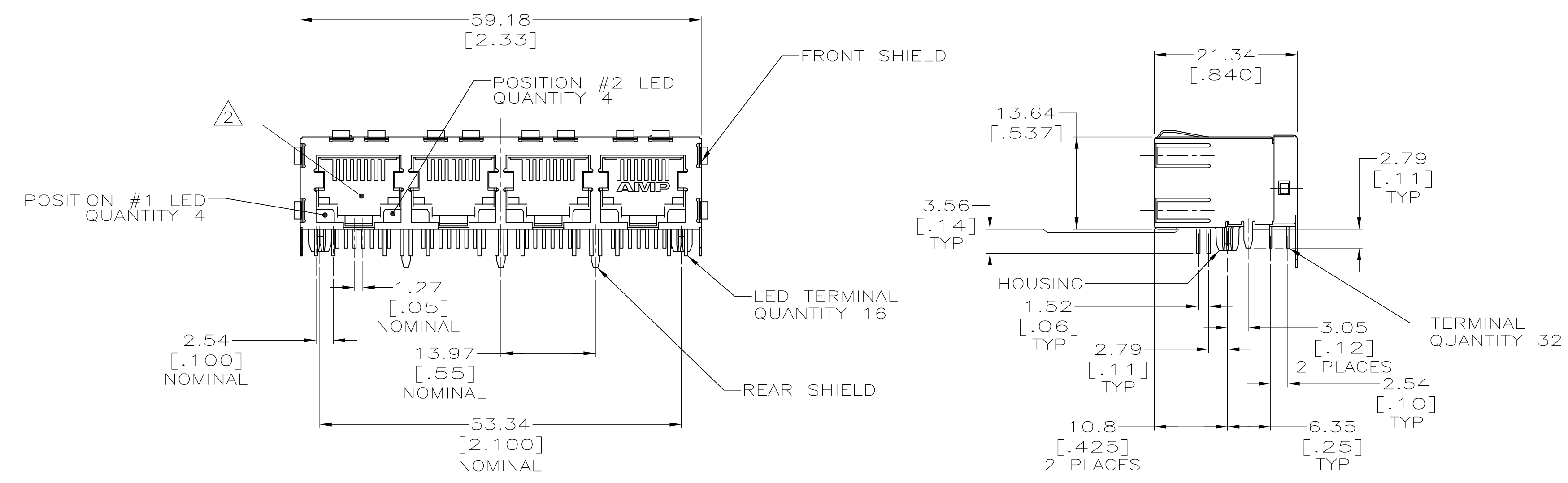
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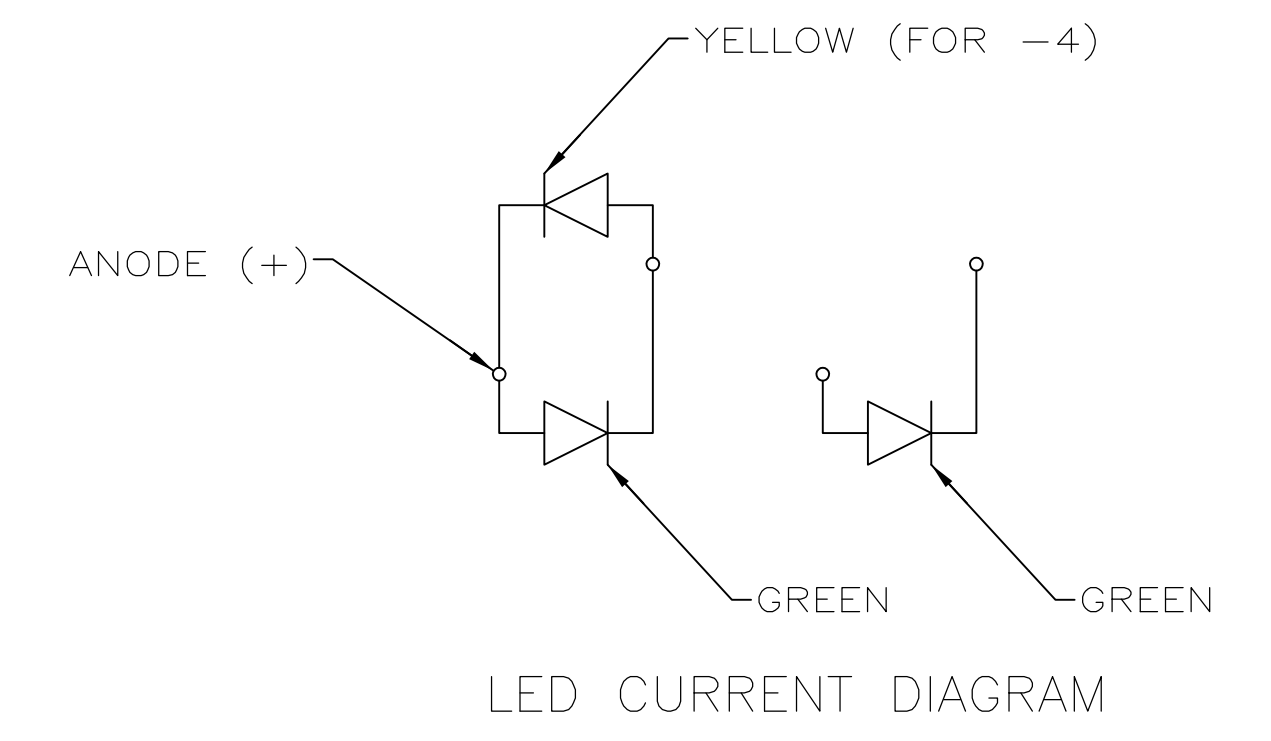
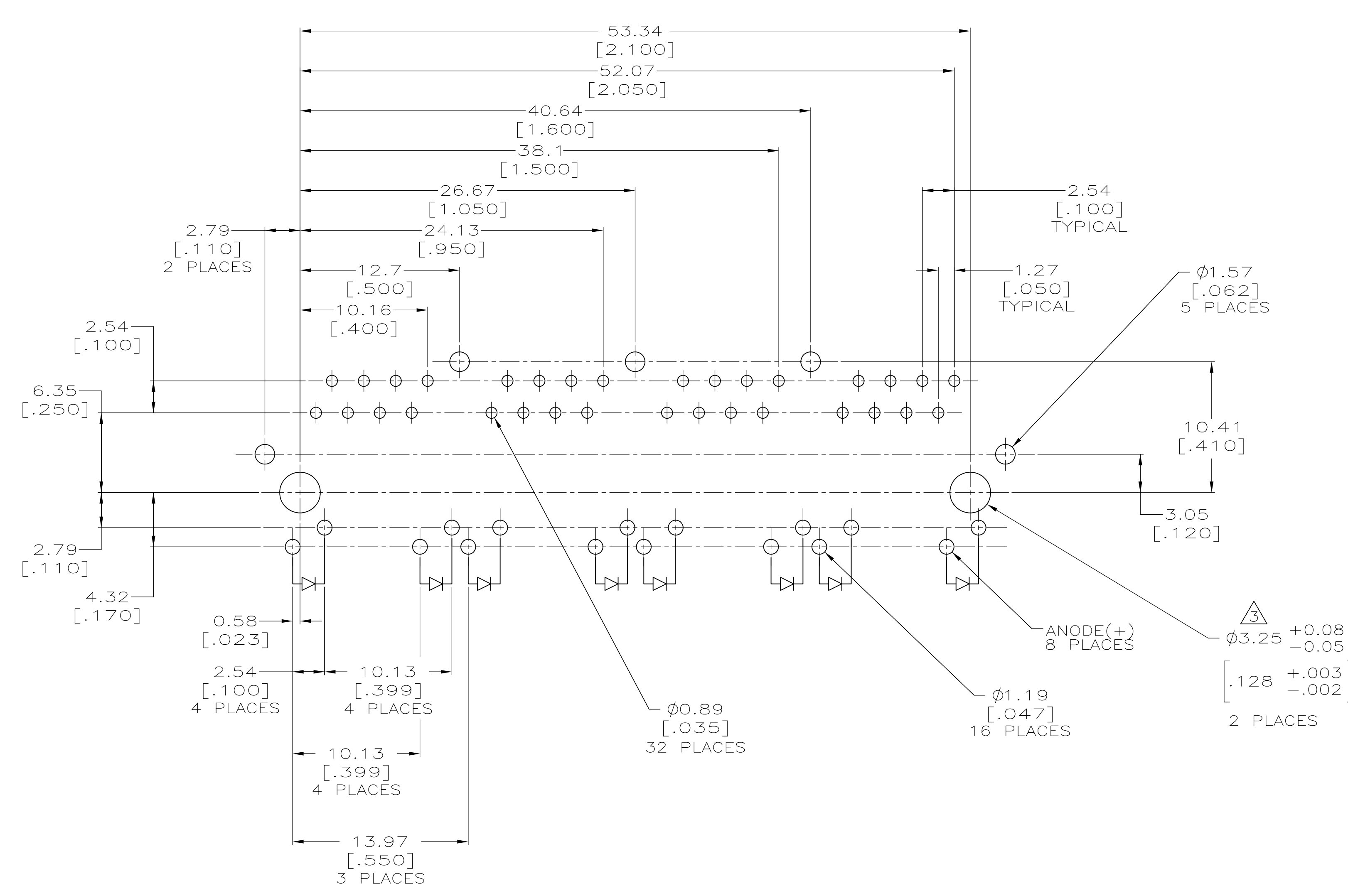
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



LOC		DIST		REVISIONS			
F	LTR	DESCRIPTION	DATE	DN	APVD		
B		REV PER ECR-08-032447	23FEB2009	DZ	SY		
B1		REVISED PER ECO-10-000444	19JAN10	KK	HMR		



- 1 MATERIAL: HOUSING - HIGH TEMPERATURE NYLON THERMOPLASTIC, BLACK, UL94V-0.
 TERMINALS - 0.33[.013] THICK PHOS BRONZE PLATED WITH 1.27 μ m[.000050] MINIMUM THICK HARD GOLD IN LOCALIZED AREA AND 3.81 μ m[.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA OVER 1.27 μ m[.000050] MINIMUM THICK NICKEL UNDERPLATE.
 SHIELD - 0.254[.010] THICK COPPER ALLOY PLATED WITH 1.27 μ m[.000050] MINIMUM NICKEL AND 2.03 μ m[.000080] MINIMUM HOT TIN DIP ON PCB GROUND TABS.
 LIGHT EMITTING DIODE (LED) - DIFFUSED EPOXY LENS, 0.51 x 0.51[.020 x .020] CARBON STEEL WIREFRAME LEADS PREPLATED WITH 8.89 μ m[.0003500] THICK Sn/Cu OVER 2.03 μ m[.000080] THICK Ag OVER 1.02 μ m[.000040] THICK Cu OVER 3.56 μ m[.000140] THICK Ni OVER 1.02 μ m[.000040] Cu UNDERPLATE
- 2 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68 SUBPART F.
- 3 USE #30 DRILL BIT OR 3.25mm DRILL BIT WHEN PRODUCING THESE PRINTED CIRCUIT BOARD HOLES.
- 4 THIS MODULAR JACK WITH INTEGRATED LEDS IS NOT IR REFLOW SOLDERING PROCESS COMPATIBLE.
- 5 OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI



SUGGESTED PC BOARD LAYOUT
 COMPONENT SIDE
 SCALE 4:1

LED POSN#1(LEFT)	LED POSN#2(RIGHT)	PART NUMBER
GREEN/YELLOW	GREEN	6116125-4
GREEN	GREEN	6116125-2
GREEN	YELLOW	6116125-1

THIS DRAWING IS A CONTROLLED DOCUMENT.		DIN L. VARELA - DOCKS 08JUN2005 CHK J. WESTMAN 08JUN2005 APVD S. FLICKINGER 08JUN2005		Tyco Electronics Corporation Harrisburg, PA 17105-3608	
DIMENSIONS: mm[inches] TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± - 1 PLC ± - 2 PLC ± 0.25[.01] 3 PLC ± 0.13[.005] 4 PLC ± - ANGLES ± -		NAME: MODULAR JACK ASSEMBLY, 4 PORT, 8 POSITION, RIGHT ANGLE, PANEL GROUND WITH LED PRODUCT SPEC: 108-1163 APPLICATION SPEC: 114-2154		SIZE: A1 CAGE CODE: 00779 DRAWING NO: 6116125 RESTRICTED TO: -	
MATERIAL: △		FINISH: △		CUSTOMER DRAWING	
		SCALE: 2:1		SHEET 1 OF 1 REV B1	